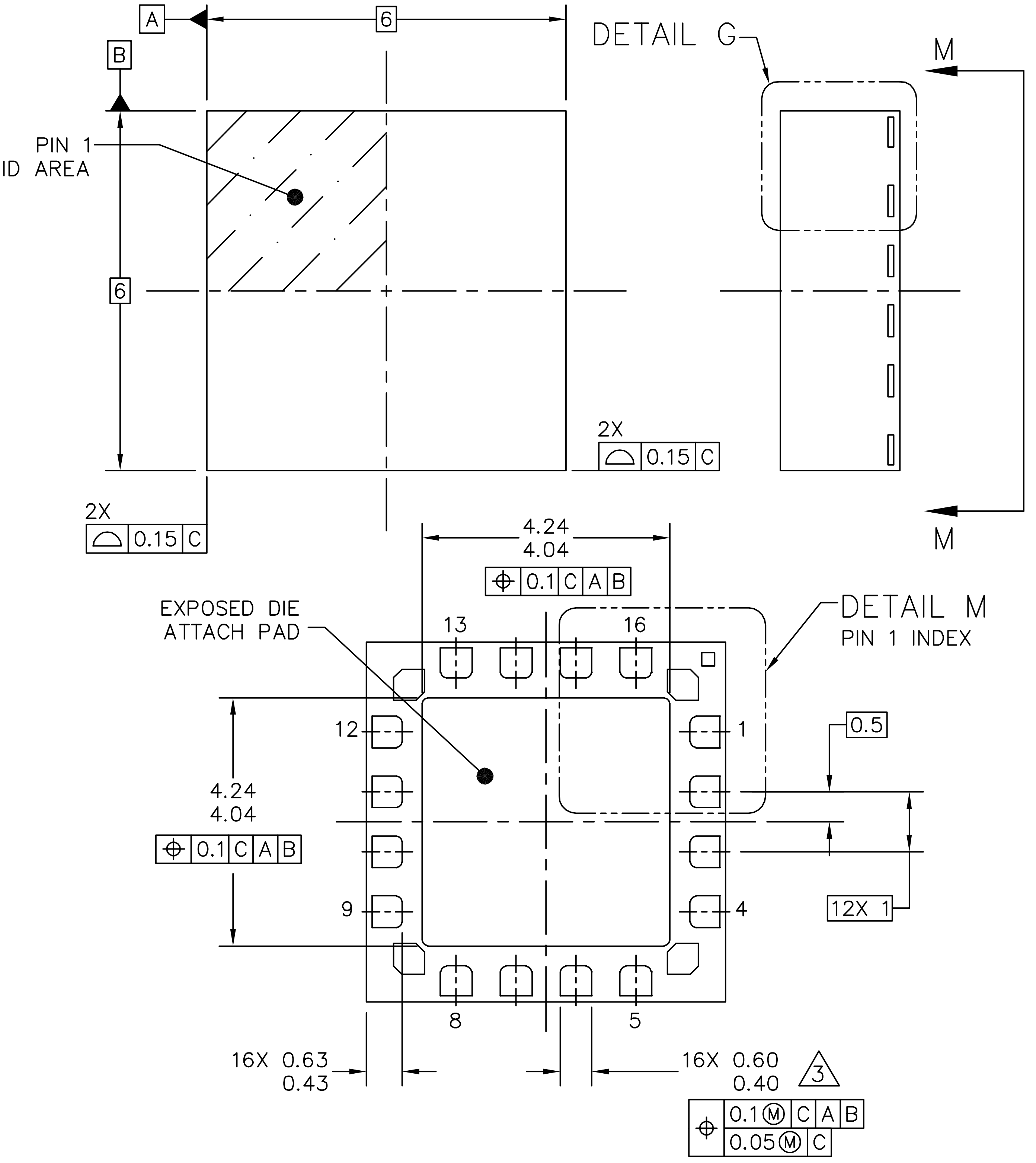

VIEW M–M

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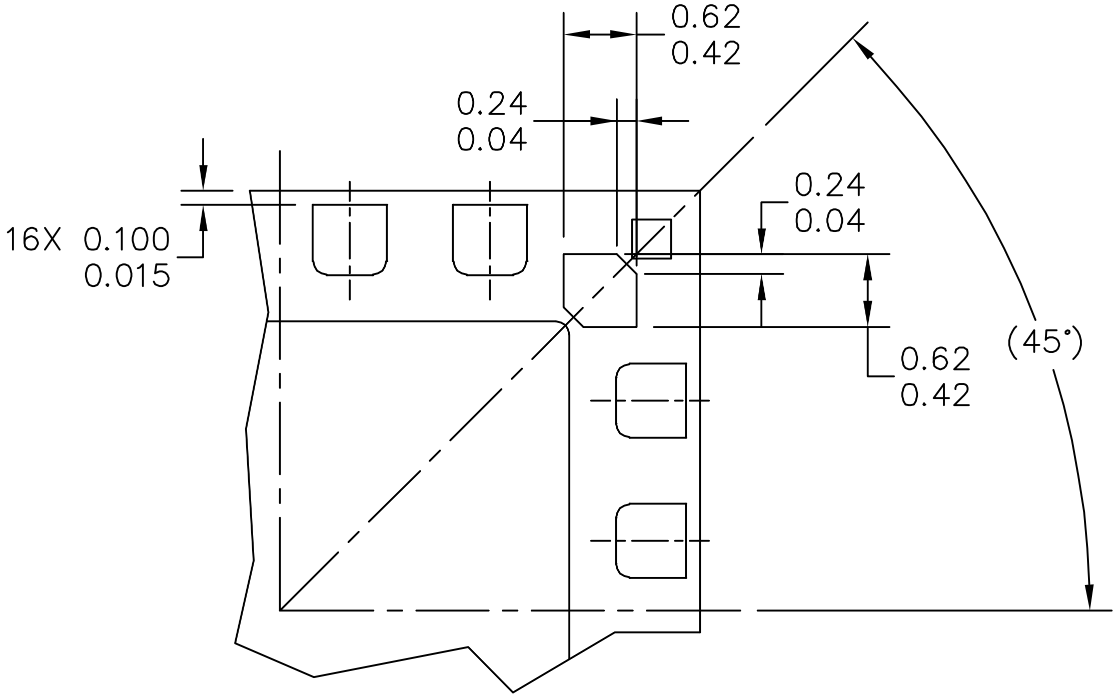
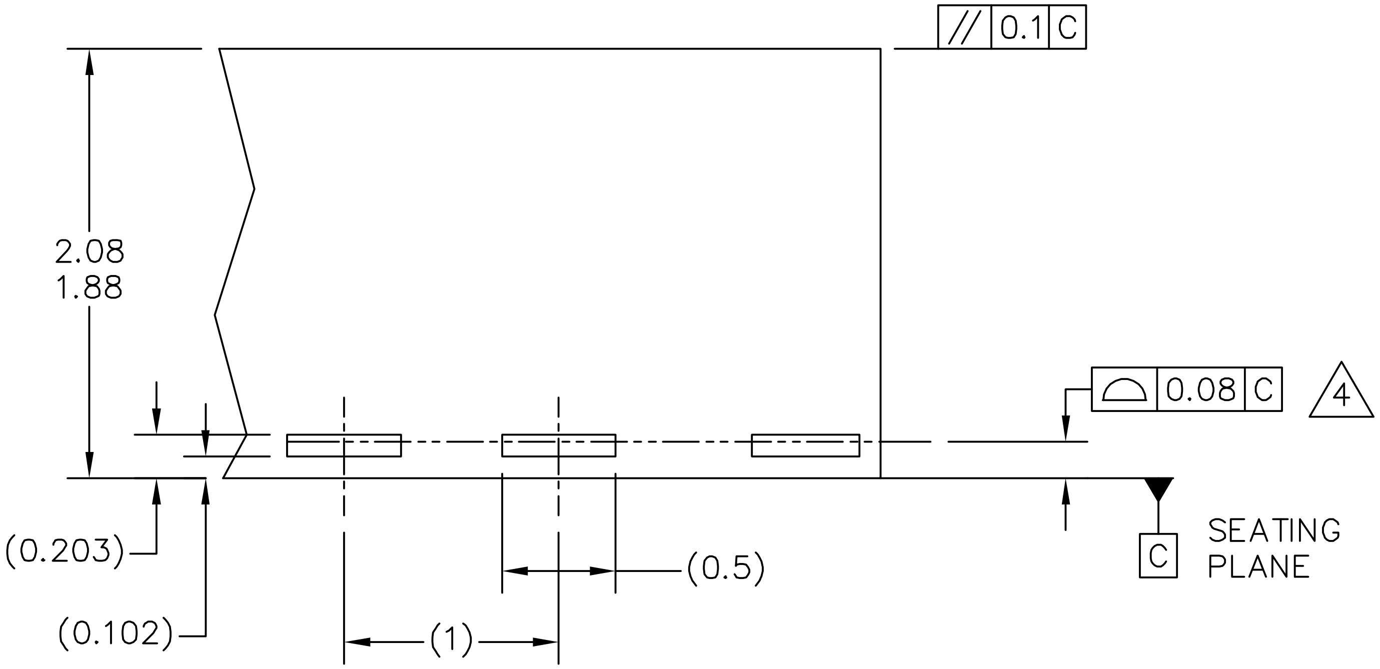
TITLE: QUAD FLAT NON–LEADED PACKAGE (QFN) FOR SENSORS 16 TERMINAL, 1.0 PITCH (6 X 6 X 1.98)	DOCUMENT NO: 98ASA10571D REV: D
	STANDARD: NON–JEDEC
	SOT1574–2 10 MAR 2016



DETAIL M



DETAIL G

VIEW ROTATED 90° CW

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
QUAD FLAT NON–LEADED
PACKAGE (QFN) FOR SENSORS
16 TERMINAL, 1.0 PITCH (6 X 6 X 1.98)

DOCUMENT NO: 98ASA10571D REV: D

STANDARD: NON–JEDEC

SOT1574–2 10 MAR 2016

NOTES:

1. ALL DIMENSIONS ARE IN MILLMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25MM AND 0.30MM FROM TERMINAL TIP.

4. COPLANARITY APPLIES TO THE EXPOSED HEAT SLUG, TERMINALS AND CORNER PADS.

5. RADIUS ON TERMINAL IS OPTIONAL.

6. MINIMUM METAL GAP SHOULD BE 0.2MM EXCEPT GAP BETWEEN CORNER PADS AND THE EXPOSED HEAT SLUG.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
QUAD FLAT NON-LEADED
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16 TERMINAL, 1.0 PITCH (6 X 6 X 1.98)

DOCUMENT NO: 98ASA10571D
REV: D

STANDARD: NON-JEDEC

SOT1574-2
10 MAR 2016